



(2.54 mm) .100"

BBS, BBL, BHS, BBD, BDL SERIES

MACHINED BOARD STACKING STRIPS

Mates with:

SS, SD, HSS, SL, SDL, ESS, ESD

FEATURES

- Low-profile design achieves (3.89 mm) .153" board spacings when mated with SL Series.
- Approach the reliability of a permanent connection with the flexibility of a separable connection.

SPECIFICATIONS

For complete specifications see www.samtec.com?BBS, www.samtec.com?BBL, www.samtec.com?BHS, www.samtec.com?BBD or www.samtec.com?BDL

Insulator Material:
Black Liquid Crystal Polymer (BBL, BHS)
Black Glass Filled Polyester (BBS, BBD, BDL)

Temperature Range:
-55 °C to +125 °C

Terminal Material:
Phosphor Bronze or Brass

Plating:

Au or Sn over
50 μ" (1.27 μm) Ni

Lead-Free Solderable:

Yes (BBL, BDL, BHS-S)
No, Lead Wave only
(BBS, BBD, BHS-N)

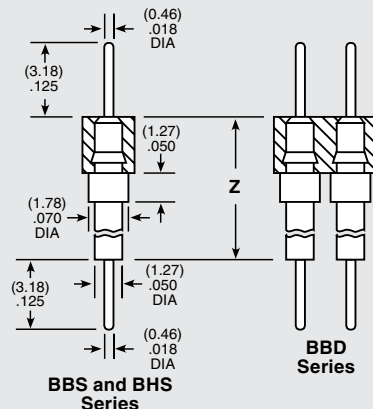
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

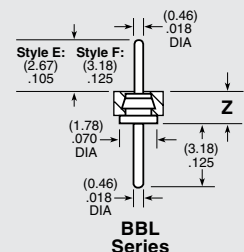


Note:
Some lengths, styles and options are non-standard, non-returnable.

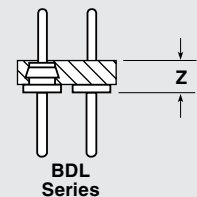
TYPE STRIP	1	NO. PINS PER ROW	PLATING OPTION	LEAD STYLE
BBS = Standard Single Row BBL = Low-Profile Single Row BHS = High Temp Single Row			-G = 20 μ" (0.51 μm) Gold -T = Tin	
BBD = Standard Double Row BDL = Low-Profile Double Row			01 thru 32 = BBS & BBL 01 thru 36 = BBD, BDL & BHS	
				-A Z = (5.33 mm) .210" -B Z = (8.51 mm) .335" -C Z = (14.86 mm) .585" -E Z = (1.78 mm) .070" -F Z = (2.16 mm) .085"



BBS and BHS Series



BBL Series



BDL Series